- 1 1. A method comprising:
- 2 forming a heat transfer fin of a laminate of two
- 3 different materials; and
- 4 permanently securing said fin to a heat
- 5 conductive base.
- 1 2. The method of claim 1 wherein forming said fin
- 2 includes forming a laminate of metallic and non-metallic
- 3 material.
- 1 3. The method of claim 1 including securing said
- 2 laminate to the base using crimping.
- 1 4. The method of claim 2 including adhesively
- 2 bonding said metallic and non-metallic materials.
- 1 5. The method of claim 1 wherein forming a heat
- 2 transfer fin includes forming a fin of a laminate of a
- 3 metallic and a pyrolytic graphite material.
- 1 6. The method of claim 1 including forming the fin
- 2 with an aspect ratio higher than 20:1.
- 1 7. The method of claim 5 including forming the fin
- 2 with an aspect ratio of 60:1.

- 1 8. The method of claim 1 including securing heat
- 2 transfer fin to an integrated circuit.
- 1 9. The method of claim 8 including securing said
- 2 heat transfer fin to a microprocessor.
- 1 10. The method of claim 2 including forming the
- 2 metallic and non-metallic material of equal thicknesses.
- 1 11. A heat sink comprising:
- a heat sink fin including two different
- 3 materials; and
- a conductive base, said fin secured to said base.
- 1 12. The heat sink of claim 11 wherein one of said
- 2 materials is metallic and the other is non-metallic.
- 1 13. The heat sink of claim 11 wherein said fin is
- 2 crimped to said base.
- 1 14. The heat sink of claim 12 wherein said metallic
- 2 and non-metallic materials are adhesively bonded.
- 1 15. The heat sink of claim 12 wherein said non-
- 2 metallic material is a pyrolytic graphite material.

- 1 16. The heat sink of claim 11 wherein the fin aspect
- 2 ratio is higher than 20:1.
- 1 17. The heat sink of claim 16 wherein the fin aspect
- 2 ratio is 60:1.
- 1 18. The heat sink of claim 11 wherein said base is
- 2 secured to an integrated circuit.
- 1 19. The heat sink of claim 18 wherein said integrated
- 2 circuit is a microprocessor.
- 1 20. The heat sink of claim 11, said fin including a
- 2 first sheet of metallic material and a second sheet of non-
- 3 metallic material, said sheets being laminated together.
- 1 21. The heat sink of claim 20 wherein said first and
- 2 second sheets are of equal thicknesses.
- 1 22. An integrated circuit comprising:
- an integrated circuit chip; and
- a heat sink secured to said chip, said heat sink
- 4 including a heat transfer fin of a laminate of metallic and
- 5 non-metallic material.

- 1 23. The circuit of claim 22 wherein said fin is
- 2 crimped to said base.
- 1 24. The circuit of claim 22 wherein said metallic and
- 2 non-metallic materials are adhesively bonded.
- 1 25. The circuit of claim 22 wherein said non-metallic
- 2 material is a pyrolytic graphite material.
- 1 26. The circuit of claim 22 wherein the fin aspect
- 2 ratio is higher than 20:1.
- 1 27. The circuit of claim 26 wherein the fin aspect
- 2 ratio is 60:1.
- 1 28. The circuit of claim 22 wherein said base is
- 2 secured to an integrated circuit.
- 1 29. The circuit of claim 28 wherein said integrated
- 2 circuit chip is a microprocessor.
- 1 30. The circuit of claim 22 wherein said metallic and
- 2 non-metallic material are of equal thicknesses.